

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer	Alternate PartNumber	Alternate Manufacturer
!PCB1	1		Printed Circuit Board		PMP10364 rev B	Any		
C2	1	22.6k	RES, 22.6 k, 1%, 0.063 W, 0402	0402	CRCW040222K6FKED	Vishay-Dale		
C4	0	DNP	CAP, CERM, 0.01uF, 25V, +/-10%, X7R, 0402	0402	C1005X7R1E103K	TDK		
C5	1	330pF	CAP, CERM, 330pF, 50V, +/-5%, C0G/NP0, 0402	0402	C1005C0G1H331J	TDK		
C6	1	1uF	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603	0603	GRM188R71E105KA12 D	MuRata		
C7, C8	2	4.7uF	CAP, CERM, 4.7uF, 10V, +/-20%, X5R, 0402	0402	GRM155R61A475M	MuRata		
C9	1	0.1uF	CAP, CERM, 0.1 uF, 25 V, +/- 10%, X5R, 0402	0402	GRM155R61E104KA87 D	MuRata		
C10, C16	2	1000pF	CAP, CERM, 1000pF, 50V, +/-10%, X7R, 0402	0402	C1005X7R1H102K	TDK		
C11, C12, C13, C14	4	22uF	CAP, CERM, 22 uF, 25 V, +/- 10%, X5R, 1210	1210	GRM32ER61E226KE15 L	MuRata		
C15	1	0.1uF	CAP, CERM, 0.1uF, 25V, +/-5%, X7R, 0603	0603	C0603C104J3RACTU	Kemet		
C17, C18	2	100uF	CAP, CERM, 100uF, 6.3V, +/-20%, X5R, 1210	1210	C1210C107M9PACTU	Kemet		
C19, C20	2	470uF	CAP, AL, 470uF, 2.5V, +/-20%, 9 ohm, SMD	7.3x1.8x4.3mm	EEFSX0E471ER	Panasonic		
C22, C24, C25, C26	4	0.1uF	CAP, CERM, 0.1uF, 50V, +/-20%, X7R, 0402	0402	C1005X7R1H104M	TDK		
C23	1	1uF	CAP, CERM, 1uF, 10V, +/-10%, X5R, 0402	0402	GRM155R61A105KE15 D	MuRata		
C27	1	100uF	CAP, AL, 100uF, 25V, +/-20%, 0.13 ohm, TH	Cap D8.0x11.5mm	UBT1E101MPD1TD	Nichicon		
C81	1	47pF	CAP, CERM, 47 pF, 25 V, +/- 5%, C0G/NP0, 0402	0402	GRM1555C1E470JA01 D	MuRata		
C82	1	6800pF	CAP, CERM, 6800 pF, 25 V, +/- 10%, X7R, 0402	0402	GRM155R71E682KA01 D	MuRata		
C83	1	1500pF	CAP, CERM, 1500 pF, 50 V, +/- 10%, X7R, 0402	0402	GRM155R71H152KA01 D	MuRata		
D1, D2	2	30V	Diode, Schottky, 30V, 0.5A, SOD-123	SOD-123	MBR0530T1G	ON Semiconductor		
D3	1	Red	LED, Red, SMD	LED_0805	LTST-C170KRKT	Lite-On		
D4	1	30V	Diode, Schottky, 30V, 0.2A, SOD-323	SOD-323	BAT54WS-7-F	Diodes Inc.		
H1, H2, H3, H4	4		Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw	NY PMS 440 0025 PH	B&F Fastener Supply		
H5, H6, H7, H8	4		Standoff, Hex, 0.5" L #4-40 Nylon	Standoff	1902C	Keystone		
J1	1		Header (shrouded), 100mil, 5x2, Gold, TH	5x2 Shrouded header	5103308-1	TE Connectivity		
J2	1		Connector, DC Jack 2.1X5.5 mm, TH	POWER JACK, 14.4x11x9mm	PJ-102A	CUI Inc.		
J3	1		TERMINAL BLOCK 5.08MM VERT 2POS	TERM_BLK, 2pos, 5.08mm	ED120/2DS	On-Shore Technology		
J4, J5	2		Header, 100mil, 2x1, Tin, TH	Header, 2 PIN, 100mil, Tin	PEC02SAAN	Sullins Connector Solutions		
L1	1	330nH	Inductor, Ferrite, 330nH, 32.8A, 0.00033 ohm, SMD	SMD, 2-Leads, Body 10.2x10mm	VLB10090HT-R33K-B2	TDK		
LBL1	1		Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650"H x 0.200"W	THT-14-423-10	Brady		
Q1	0	DNP	Transistor, NPN, 40V, 0.2A, SOT-23	SOT-23	MMBT3904	Fairchild Semiconductor		
Q2	1	25V	MOSFET, N-CH, 25V, 40A, SON 5x6mm	SON 5x6mm	CSD16556Q5B	Texas Instruments		None
R1, R26	2	100k	RES, 100k ohm, 1%, 0.063W, 0402	0402	CRCW0402100KFKED	Vishay-Dale		
R3, R5	0	Open	RES, 0 ohm, 5%, 0.063W, 0402	0402	OPEN	Panasonic		
R4	0	Open	RES, 20.0k ohm, 1%, 0.063W, 0402	0402	OPEN	Vishay-Dale		
R6	1	10.0k	RES, 10.0 k, 1%, 0.063 W, 0402	0402	CRCW040210K0FKED	Vishay-Dale		
R7, R13, R15	3	49.9	RES, 49.9 ohm, 1%, 0.063W, 0402	0402	CRCW040249R9FKED	Vishay-Dale		
R8	1	49.9k	RES, 49.9 k, 1%, 0.063 W, 0402	0402	CRCW040249K9FKED	Vishay-Dale		
R9	0	DNP	RES, 191 k, 1%, 0.063 W, 0402	0402	DNP	Vishay-Dale		
R10, R17	2	0	RES, 0 ohm, 5%, 0.063W, 0402	0402	RC0402JR-070RL	Yageo America		
R11, R12	2	34.8k	RES, 34.8 k, 1%, 0.063 W, 0402	0402	CRCW040234K8FKED	Vishay-Dale		



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